

APPARATUS AND METHOD FOR MOUNTING ELECTRONIC COMPONENT

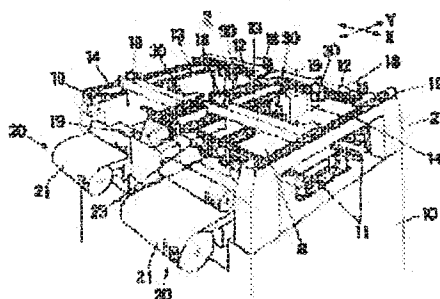
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Abstract of JP 11289194 (A)

PROBLEM TO BE SOLVED: To mount electronic components to a substrate with high workability and at a high speed by using a plurality of devices for mounting electronic components and to change the layout flexibly in accordance with the change in the kinds of the substrates. **SOLUTION:** This apparatus is formed by arranging a plurality of unit devices 2 for mounting electronic components side by side. A conveying route 11 is provided to the center of the upper surface of a base 10, and the device 2 is provided with an XY-table mechanism comprising a feed screw 12 in an X-direction, a feed screw 13 in a Y-direction and motors 18 and 19. A total of four head parts 30 are provided to the respective XY-table mechanism, so as to convey and mount the electronic components of an electronic component supply part 20 to the board. The head part 30 is provided with a plurality of nozzles such as a circle and picks up a plurality of electronic components at the same time and does the recognition of the positions thereof as well.



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